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(71) Applicants: **MERCK PATENT GMBH** [DE/DE]; Frankfurt Strasse 250, 64293 Darmstadt (DE). **VERSUM MATERIALS US, LLC** [US/US]; 8555 South River Parkway, Tempe, Arizona 85284 (US).

(72) Inventors: **MAI, Lukas**; Merck Electronics KGaA, Frankfurt Strasse 250, 64293 Darmstadt (DE). **MEHLMANN, Paul**; Merck Electronics KGaA, Frankfurt Strasse 250, 64293 Darmstadt (DE). **MATURI, Mark**; Merck Electron-

ics KGaA, Frankfurt Strasse 250, 64293 Darmstadt (DE). **HEIL, Holger**; Merck Electronics KGaA, Frankfurt Strasse 250, 64293 Darmstadt (DE). **IVANOV, Sergei**; Versum Materials US, LLC, 8555 South River Parkway, Tempe, Arizona 85284 (US).

(74) Agent: **SLAVEN, William T., IV**; Versum Materials US, LLC, 8555 South River Parkway, Tempe, Arizona 85284 (US).

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(54) Title: INTRAMOLECULAR STABILIZED METAL COMPLEXES WITH IMPROVED THERMAL STABILITY FOR VAPOR PHASE THIN-FILM DEPOSITION TECHNIQUES

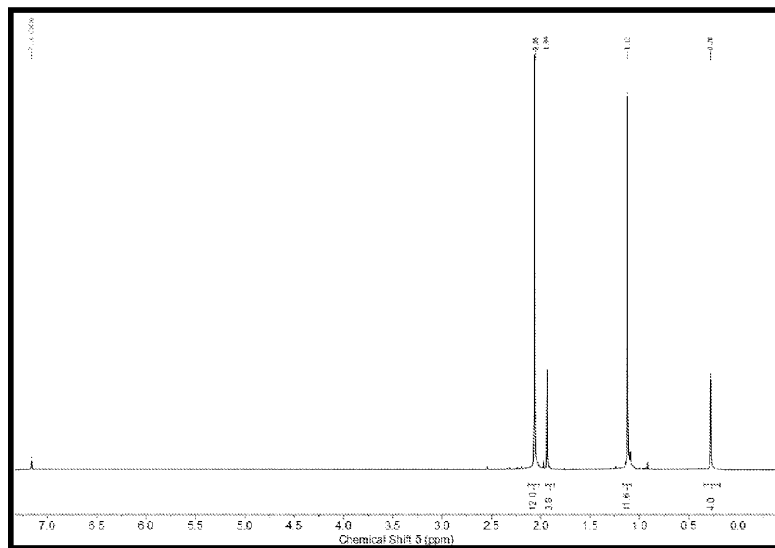


FIG. 1

(57) Abstract: The disclosed and claimed subject matter relates to copper (Cu), zinc (Zn), cadmium (Cd), magnesium (Mg), calcium (Ca), strontium (Sr) and barium (Ba) compounds and methods of using the compounds as precursors for deposition of metal-containing films.

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